Compliant with IEC 62474/ D9.00

MICROCHIP  Semiconductor Device Type: (PFA) 032 VQFN 5x5x0.9 Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling
									e3	
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	24.81	(mg) Total	Mold Compound	% ot Total Weight	40.41
Silica, fused	60676-86-0	Mold Compound	36.369	22.331	363,690		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	1.960	1.203	19,599		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	1.960	1.203	19,599		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.121	0.074	1,212		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	51.695	31.741	516,953	•		Total	100.00	
Iron	7439-89-6	Lead Frame	1.272	0.781	12,716	33.22	(mg) Total	Lead Frame	% of Total Weight	54.11
Silver	7440-22-4	Lead Frame	1.031	0.633	10,308		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.068	0.042	676		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.045	0.027	446		Silver	7440-22-4	1.91	
Silver	7440-22-4	Die Attach	0.451	0.277	4,514		Zinc	7440-66-6	0.13	
Epoxy resin	Trade Secret	Die Attach	0.140	0.086	1,403		Phosphorous	7723-14-0	0.08	
Metal oxide	Trade Secret	Die Attach	0.018	0.011	183			Total	100.00	•
Silicon	7440-21-3	Chip (Die)	1.650	1.013	16,500	0.37	(mg) Total	Die Attach	% of Total Weight	0.61
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	1.621	0.995	16,211		Silver	7440-22-4	74.00	
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.029	0.018	289		Epoxy resin	Trade Secret	23.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.570	0.964	15,700		Metal oxide	Trade Secret	3.00	
		TOTALS:	100.000	61.400	1,000,000			Total	100.00	
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	with EU Directives	g Total Mass				1.01	Total (mg)  Doped Silicon	Chip (Die) 7440-21-3	% of Total Weight	1.65
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